

Editorial

It is our great pleasure to announce the publication of JSTS special issue on “Special Issue on System Integration Technologies for Wireless Terminals”. This special issue intends to gather and disseminate the most recent advances in the field of various integrated system technologies including fabrication process, modeling and simulation, concepts, architectures, building blocks, circuits and systems.

The first two papers by Mitiko Miura-Mattausch group and B. Iñiguez et al. dealt with the new MOS device modeling approaches especially for RF applications. This is followed by an overview of on-chip spiral inductors for RF applications by Ji Chen and Juin J. Liou. Next paper treats receiver dynamic range optimized CMOS baseband circuit design by M. Lee et al., which is followed by system level test beds of multi-standard receiver by Changjae Kim et al. These are then followed by 3 system level packaging technologies, i.e., a System-in-Package (SiP) integration of a 62GHz transmitter technology by Young Chul Lee and Chul Soon Park, a wafer level packaged amplifier for 10Gbps optical transmission system by C. W. Ju, and wafer-level three-dimensional monolithic integration technology for wireless terminals paper from Prof. R.J. Gutmann’s group in RPI.

Next two papers deal with MODEM issues, first one by H.C. Park dealing with low power implementation of matched filter, and second one dealing with UWB communication system by Suckchel Yang et al.

We would like to express sincerely thanks to all authors from all over the world for submitting such an excellent papers touching very timely issue of wireless technologies and sharing their research progress with us.

Kwyro Lee
Editor-in-Chief
Dept. of EECS, KAIST
373-1 Kusong, Yuseong, Korea